


THERMAL PASTE

series: ATP

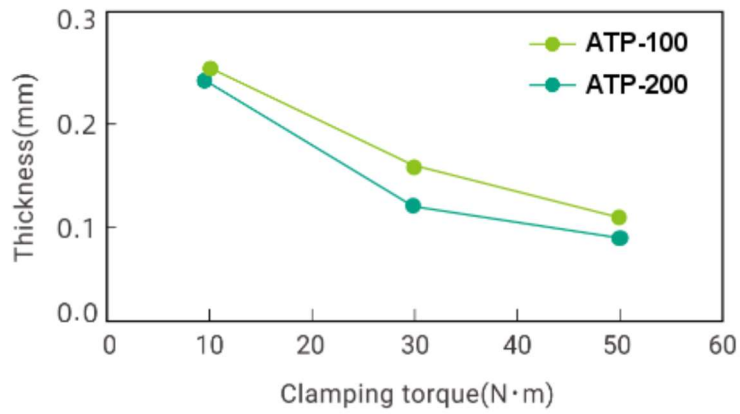


- Eliminates air gaps between heat source and heat sink.
- High thermal conductivity of up to 6.5w/mk.
- Molecular structure prevents leakage and vaporization.
- Long term reliability.
- Good electrical insulation.
- Low rebound reduces load on electronic components.
- Compresses easily, absorbing dimensional tolerances.
- Typical applications include PCBs in automotive navigation systems, CIDs and ECUs, tablet devices, digital cameras, digital signage and manufacturing equipment.

Properties		ATP-100
Thermal Conductivity (W/m-k) – Our tests		6.5
Hot wire method		2.0
Hardness (Cone Penetration (1/10mm), not mixed)		51
Appearance		Gray
Specific Gravity		2.8
Volume Resistivity (Ω.cm)		5.9x10
Dielectric Breakdown Strength (kV/mm)		5.0
Dielectric Constant <50Hz>		8.9
<1KHz>		7.8
<1MHz>		7.0
Dielectric Dissipation Factor <50Hz>		0.234
<1KHz>		0.061
<1MHz>		0.015
Thermal Resistance (°C/W) Transistor: MT-200 Heat Input: 20V	Thickness (mm) 0.10	-
	0.15	0.13
	0.20	0.15
	0.30	0.18
Low Molecular Weight Siloxane Level D4-10 (ppm)	Solvent Extraction Method	Less than 700
	Head Space Method	Less than 1
Temperature Range (°C)		-40 ~ 200

Clamping Torque Dependency

Transistor: MT-200Type Area: 7.7cm²



Thermal Resistance

Thickness (mm)	0.10	0.15	0.20	0.30
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 Heat input: 20W
 (°C)